Pore Sealing Technology For Gold Plated Electronic & Interconnect Components

APT-PST™ (Pore Sealing Technology) is a gold post-plate treatment which protects the gold surface from corrosion while enhancing lubricity. This thin, transparent layer acts as a porosity sealant allowing for a thinner layer of gold to be plated to meet accelerated porosity and corrosion test requirements. The process is halogen free and does not use any regulated RoHS or ELV elements or compounds. The treatment is thermally stable up to 260C and does not degrade the solderability or conductivity of the gold.

Key Attributes of APT-PST™ are as follows:
• Improved corrosion resistance in porosity tests such as nitric acid
• Enhanced lubricity for sliding interconnect or contact components
• Allows for reduced gold consumption to meet performance requirements
• No effect on the gold electrical properties
• Does not impede solderability
• Does not increase resistivity of the gold plated layer
• Fully RoHS & ELV Compliant
• Dry to touch after layer is applied
• Does not add any appreciable thickness to the plated layers

Learn More About APT-PST™ & Gold Plating

Visit Advanced Plating Technologies online at: www.AdvancedPlatingTech.com
Contact a member of our technical sales team at: Sales@AdvancedPlatingTech.com